

# Solder paste NP303-WS6157-T6

## Product description

GENMA solder paste – our NP303-WS6157-T6 solder paste with water soluble flux. It convinces with its outstanding printability, highly precise contours, long open time, and consistent adhesiveness in the pick-and-place process. Its extremely good wetting properties, also on difficult surfaces, produce perfect soldering joints on BGAs. Hardly any voids in the solder connections. Cleaning of flux residues with water after soldering is required. The solder paste can be soldered under nitrogen reflow.

## Technical properties

	Specific value	Testing method
<b>Alloy</b>	Sn 96,5 / Ag 3,0 / Cu 0,5 / SAC305	
<b>Melting temperature range</b>	217 - 221	IEC61189-11
<b>Powder size (µm)</b>	5 - 15, type 6	IPC-TM-650-2.2.14.2
<b>Viscosity (Pa · s)</b>	230 ± 60	IPC-TM-650-2.4.34.3
<b>Flux content (wt %)</b>	11 ± 0,5	IPC-TM-650-2.3.34.1
<b>Halide content (wt %)</b>	≤ 0,05	IPC-TM-650-2.3.35
<b>Migration test</b>	No migration	IPC-TM-650-2.6.14.1
<b>Copper mirror test</b>	No corrosion	IPC-TM-650-2.3.32
<b>Packaging</b>	Jar (0,5 kg) Semco cartridge (0,65 kg, 1,2 kg)	
<b>Transport</b>	Keep cool	
<b>Tempering the solder paste</b>	Set to room temperature before opening to avoid condensation.	
<b>Recommended printing speed (mm/s)</b>	20 - 80	
<b>Recommended temperature during print ( °C )</b>	25 ± 3	
<b>Recommended relative humidity in % during print</b>	50 ± 20	

## Compliance

Conform with RoHS-Regulation 2011/65/EU

Contains no substances more than threshold (0,1%) according to REACH legislation EG Nr. 1907/2006 (SVHC-list - dated 27.06.2018)